

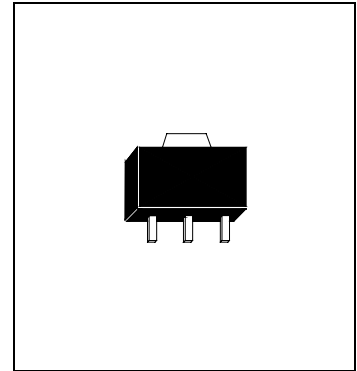


HM64

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HM64 is a darlington amplifier transistor designed for applications requiring extremely high current gain.



Features

- High D.C current gain
- HM64 is complementary to HM14

Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1 W
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -30 V
VCES Collector to Emitter Voltage -30 V
VEBO Emitter to Base Voltage -10 V
IC Collector Current -300 mA

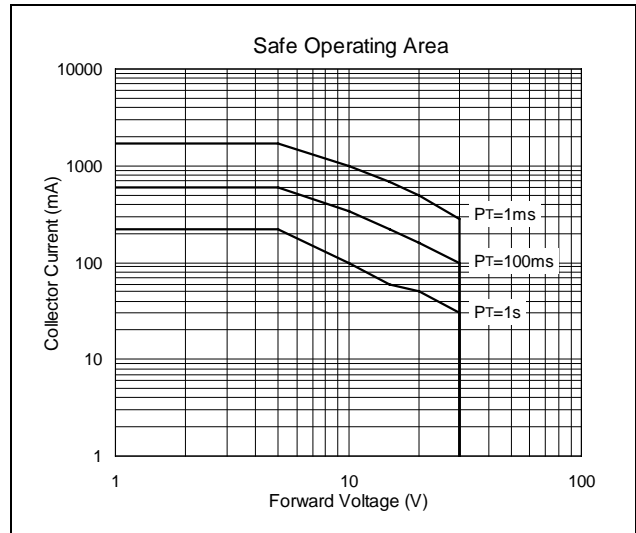
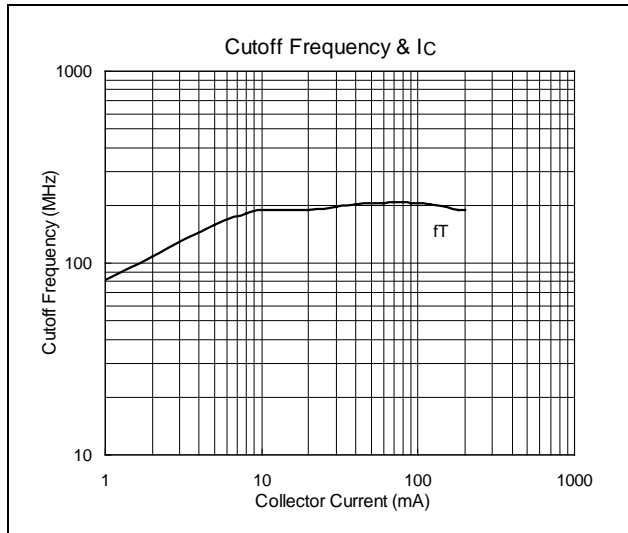
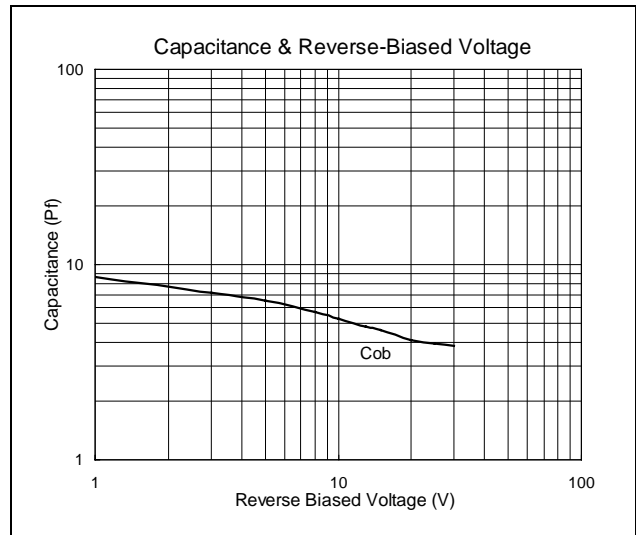
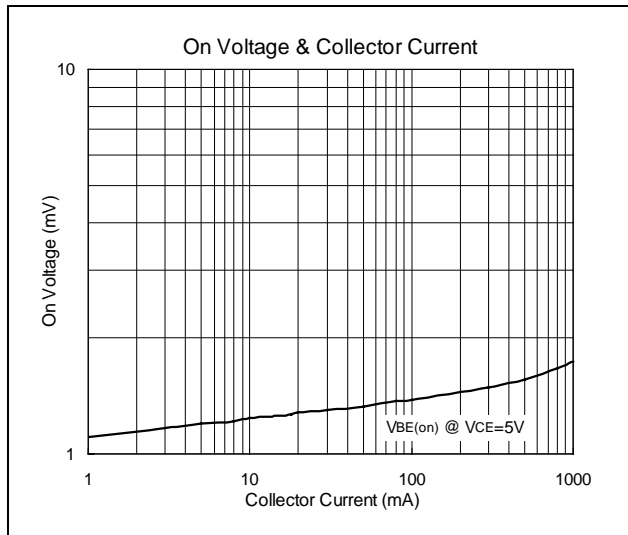
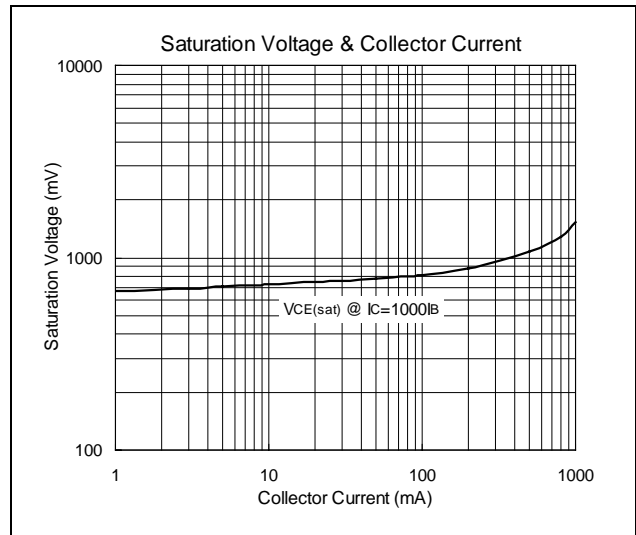
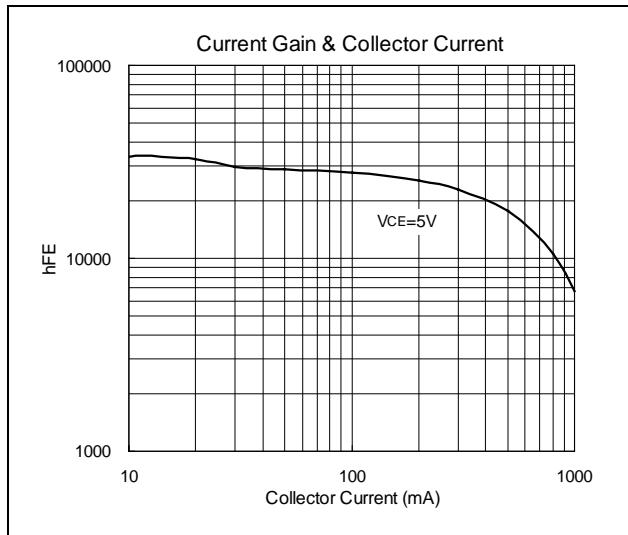
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-30	-	-	V	IC=-100uA
BVCES	-30	-	-	V	IC=-100uA
BVEBO	-10	-	-	V	IE=-10uA
ICBO	-	-	-100	nA	VCB=-30V
IEBO	-	-	-100	nA	VEB=-10V
*VCE(sat)	-	-	-1.5	V	IC=-100mA, IB=-0.1mA
*VBE(on)	-	-	-2	V	VCE=-5V, IC=-100mA
*hFE1	10	-	-	K	VCE=-5V, IC=-10mA
*hFE2	20	-	-	K	VCE=-5V, IC=-100mA
fT	125	-	-	MHz	VCE=-5V, IC=-10mA

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve





SOT-89 Dimension

Marking:

Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-89 Plastic Surface Mounted Package
 HSMC Package Code: M

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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